#### LF353 JFET-INPUT DUAL OPERATIONAL AMPLIFIER SLOS012B – MARCH 1987 – REVISED AUGUST 1994

- Low Input Bias Current . . . 50 pA Typ
- Low Input Noise Current 0.01 pA/√Hz Typ
- Low Input Noise Voltage . . . 18 nV/\Hz Typ
- Low Supply Current . . . 3.6 mA Typ
- High Input Impedance . . .  $10^{12} \Omega$  Typ
- Internally Trimmed Offset Voltage
- Gain Bandwidth . . . 3 MHz Typ
- High Slew Rate ... 13 V/μs Typ

### description

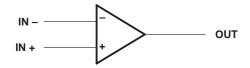
**D OR P PACKAGE** (TOP VIEW) 10UT Vcc+ 8 20UT 1IN-7 Ш 2 6 2IN-1IN+ [ 3 12IN+ 4 5 Vcc

This device is a low-cost, high-speed, JFET-input operational amplifier with very low input offset voltage. It requires low supply current yet maintains a large gain-bandwidth product and a fast slew rate. In addition, the matched high-voltage JFET input provides very low input bias and offset currents.

The LF353 can be used in applications such as high-speed integrators, digital-to-analog converters, sample-and-hold circuits, and many other circuits.

The LF353 is characterized for operation from 0°C to 70°C.

### symbol (each amplifier



#### AVAILABLE OPTIONS

	Viemox	PACKAGE				
TA	V <sub>IO</sub> max AT 25°C	SMALL OUTLINE (D)	PLASTIC DIP (P)			
0°C to 70°C	10 mV	LF353D	LF353P			

The D packages are available taped and reeled. Add the suffix R to the device type (ie., LF353DR).

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC +</sub>	
Supply voltage, V <sub>CC -</sub>	18 V
Differential input voltage, VID	±30 V
Input voltage, V <sub>I</sub> (see Note 1)	±15 V
Duration of output short circuit	unlimited
Continuous total power dissipation	500 mW
Operating temperature range	0°C to 70°C
Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

NOTE 1: Unless otherwise specified, the absolute maximum negative input voltage is equal to the negative power supply voltage.



# **LF353** JFET-INPUT DUAL OPERATIONAL AMPLIFIER

SLOS012B - MARCH 1987 - REVISED AUGUST 1994

#### recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V <sub>CC +</sub>	3.5	18	V
Supply voltage, V <sub>CC –</sub>	-3.5	-18	V

#### electrical characteristics over operating free-air temperature range, $V_{CC\pm}$ = ±15 V (unless otherwise specified)

	PARAMETER	TEST CO	NDITIONS	T <sub>A</sub> †	MIN	TYP	MAX	UNIT
\/		VIC = 0,	R <sub>S</sub> = 10 kΩ	25°C		5	10	
VIO	Input offset voltage			Full range			13	mV
αγιο	Average temperature coefficient of input offset voltage	V <sub>IC</sub> = 0,	R <sub>S</sub> = 10 kΩ			10		μV/°C
li o	+			25°C		25	100	pА
IIO	Input offset current‡	VIC = 0		70°C			4	nA
lun.	· · · · · · · · · · · · · · · · · · ·	$\lambda = 0$		25°C		50	200	pА
IВ	Input bias current‡	$A^{IC} = 0$		70°C			8	nA
VICR	Common-mode input voltage range				±11	-12 to 15		V
VOM	Maximum peak output voltage swing	$R_L = 10 \ k\Omega$			±12	±13.5		V
A		V- 10V	$\mathbf{P}_{\mathbf{k}} = 2 \mathbf{k} 0$	25°C	25	100		V/mV
AVD	Large-signal differential voltage	$V_{O} = \pm 10 V,$	$R_L = 2 k\Omega$	Full range	15			V/IIIV
ri	Input resistance	T <sub>J</sub> = 25°C				10 <sup>12</sup>		Ω
CMRR	Common-mode rejection ratio	$R_S \le 10 \ k\Omega$			70	100		dB
ksvr	Supply-voltage rejection ratio	See Note 2			70	100		dB
ICC	Supply current					3.6	6.5	mA

<sup>†</sup>Full range is 0°C to 70°C.

‡ Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive. Pulse techniques must be used that will maintain the junction temperatures as close to the ambient temperature as possible.

NOTE 2: Supply-voltage rejection ratio is measured for both supply magnitudes increasing or decreasing simultaneously.

# operating characteristics, V\_{CC\pm} = $\pm 15$ V, T\_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>01</sub> /V <sub>02</sub>	Crosstalk attentuation	f = 1 kHz		120		dB
SR	Slew rate		8	13		V/µs
B <sub>1</sub>	Unity-gain bandwidth			3		MHz
V <sub>n</sub>	Equivalent input noise voltage	f = 1 kHz, $R_S = 20 \Omega$		18		nV/√Hz
I <sub>n</sub>	Equivalent input noise current	f = 1 kHz		0.01		pA/√Hz



## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
LF353D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
LF353DR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
LF353P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

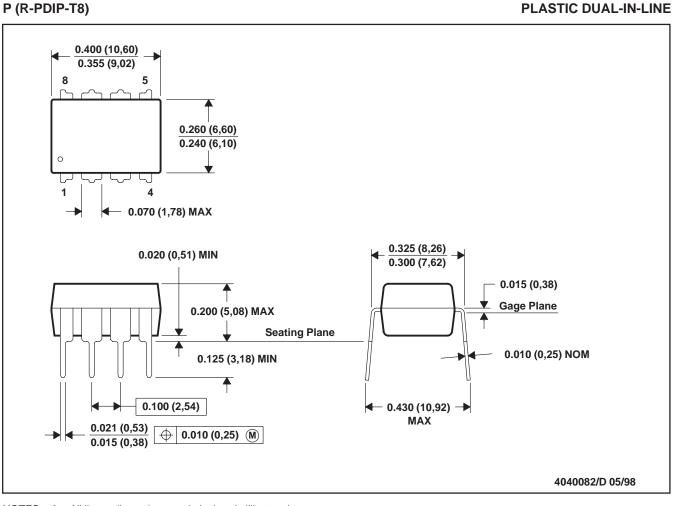
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

# **MECHANICAL DATA**

MPDI001A - JANUARY 1995 - REVISED JUNE 1999



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg\_info.htm



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AA.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.